Microchip Technology - AT40K40AL-1BQU Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	2304
Total RAM Bits	18432
Number of I/O	114
Number of Gates	50000
Voltage - Supply	3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TC)
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at40k40al-1bqu

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Reading and writing of the 10 ns 32 x 4 dual-port FreeRAM are independent of each other. Reading the 32 x 4 dual-port RAM is completely asynchronous. Latches are transparent; when Load is logic 1, data flows through; when Load is logic 0, data is latched. These latches are used to synchronize Write Address, Write Enable Not, and Din signals for a synchronous RAM. Each bit in the 32 x 4 dual-port RAM is also a transparent latch. The front-end latch and the memory latch together form an edge-triggered flip flop. When a nibble (bit = 7) is (Write) addressed and LOAD is logic 1 and $\overline{WE}$ is logic 0, data flows through the bit. When a nibble is not (Write) addressed or LOAD is logic 0 or $\overline{WE}$ is logic 1, data is latched in the nibble. The two CLOCK muxes are controlled together; they both select CLOCK (for a synchronous RAM) or they both select "1" (for an asynchronous RAM). CLOCK is obtained from the clock for the sector-column immediately to the left and immediately above the RAM block. Writing any value to the RAM clear byte during configuration clears the RAM (see the "AT40K/40KAL Configuration Series" application note at www.atmel.com).

Figure 8. RAM Logic

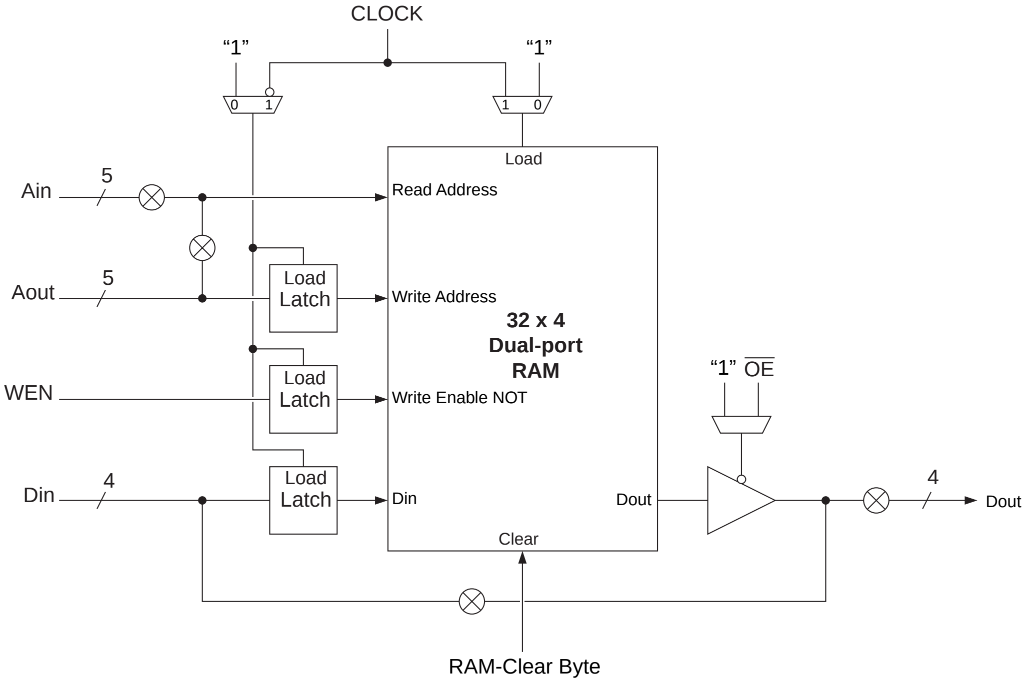


Figure 9 on page 13 shows an example of a RAM macro constructed using the AT40KAL's FreeRAM cells. The macro shown is a 128 x 8 dual-ported asynchronous RAM. Note the very small amount of external logic required to complete the address decoding for the macro. Most of the logic cells (core cells) in the sectors occupied by the RAM will be unused: they can be used for other logic in the design. This logic can be automatically generated using the macro generators.

Set/Reset Scheme

The AT40KAL family reset scheme is essentially the same as the clock scheme except that there is only one Global Reset. A dedicated Global Set/Reset bus can be driven by any User I/O, except those used for clocking (Global Clocks or Fast Clocks). The automatic placement tool will choose the reset net with the most connections to use the global resources. You can change this by using an RSBUF component in your design to indicate the global reset. Additional resets will use the express bus network.

The Global Set/Reset is distributed to each column of the array. Like Sector Clock mux, there is Sector Set/Reset mux at every four cells. Each sector column of four cells is set/reset by a Plane 5 express bus or Global Set/Reset using the Sector Set/Reset mux, see Figure 11 on page 17. The set/reset provided to each sector column of four cells is either inverted or non-inverted using the Sector Reset mux.

The function of the Set/Reset input of a register is determined by a configuration bit in each cell. The Set/Reset input of a register is active low (logic 0) by default. Setting or Resetting of a register is asynchronous. Before configuration on power-up, a logic 1 (a high) is provided by each register (i.e., all registers are set at power-up).

I/O Structure

The AT40KAL has registered I/Os and group enable every sector for tri-states on obuf's.

PAD

The I/O pad is the one that connects the I/O to the outside world. Note that not all I/Os have pads: the ones without pads are called Unbonded I/Os. The number of unbonded I/Os varies with the device size and package. These unbonded I/Os are used to perform a variety of bus turns at the edge of the array.

PULL-UP/PULL-DOWN

Each pad has a programmable pull-up and pull-down attached to it. This supplies a weak "1" or "0" level to the pad pin. When all other drivers are off, this control will dictate the signal level of the pad pin.

The input stage of each I/O cell has a number of parameters that can be programmed either as properties in schematic entry or in the I/O Pad Attributes editor in IDS.

CMOS

The threshold level is a CMOS-compatible level.

SCHMITT

A Schmitt trigger circuit can be enabled on the inputs. The Schmitt trigger is a regenerative comparator circuit that adds 1V hysteresis to the input. This effectively improves the rise and fall times (leading and trailing edges) of the incoming signal and can be useful for filtering out noise.

DELAYS

The input buffer can be programmed to include four different intrinsic delays as specified in the AC timing characteristics. This feature is useful for meeting data hold requirements for the input signal.

DRIVE

The output drive capabilities of each I/O are programmable. They can be set to FAST, MEDIUM or SLOW (using IDS tool). The FAST setting has the highest drive capability (20 mA at 5V) buffer and the fastest slew rate. MEDIUM produces a medium drive (14 mA at 5V) buffer, while SLOW yields a standard (6 mA at 5V) buffer.

TRI-STATE

The output of each I/O can be made tri-state (0, 1 or Z), open source (1 or Z) or open drain (0 or Z) by programming an I/O's Source Selection mux. Of course, the output can be normal (0 or 1), as well.

SOURCE SELECTION MUX

The Source Selection mux selects the source for the output signal of an I/O.

Primary, Secondary and Corner I/Os

The AT40KAL has three kinds of I/Os: Primary I/O, Secondary I/O and a Corner I/O. Every edge cell except corner cells on the AT40KAL has access to one Primary I/O and two Secondary I/Os.

Primary I/O

Every logic cell at the edge of the FPGA array has a direct orthogonal connection to and from a Primary I/O cell. The Primary I/O interfaces directly to its adjacent core cell. It also connects into the repeaters on the row immediately above and below the adjacent core cell. In addition, each Primary I/O also connects into the busing network of the three nearest edge cells. This is an extremely powerful feature, as it provides logic cells toward the center of the array with fast access to I/Os via local and express buses. It can be seen from the diagram that a given Primary I/O can be accessed from any logic cell on three separate rows or columns of the FPGA. See Figure 12 on page 20.

Secondary I/O

Every logic cell at the edge of the FPGA array has two direct diagonal connections to a Secondary I/O cell. The Secondary I/O is located between core cell locations. This I/O connects on the diagonal inputs to the cell above and the cell below. It also connects to the repeater of the cell above and below. In addition, each Secondary I/O also connects into the busing network of the two nearest edge cells. This is an extremely powerful feature, as it provides logic cells toward the center of the array with fast access to I/Os via local and express buses. It can be seen from the diagram that a given Secondary I/O can be accessed from any logic cell on two rows or columns of the FPGA. See Figure 13 on page 20.

Corner I/O

Logic cells at the corner of the FPGA array have direct-connect access to five separate I/Os: 2 Primary, 2 Secondary and 1 Corner I/O. Corner I/Os are like an extra Secondary I/O at each corner of the array. With the inclusion of Corner I/Os, an AT40KAL FPGA with n x n core cells always has 8n I/Os. As the diagram shows, Corner I/Os can be accessed both from the corner logic cell and the horizontal and vertical busing networks running along the edges of the array. This means that many different edge logic cells can access the Corner I/Os. See Figure 14 on page 21.

Figure 12. West Primary I/O (Mirrored for East I/O)

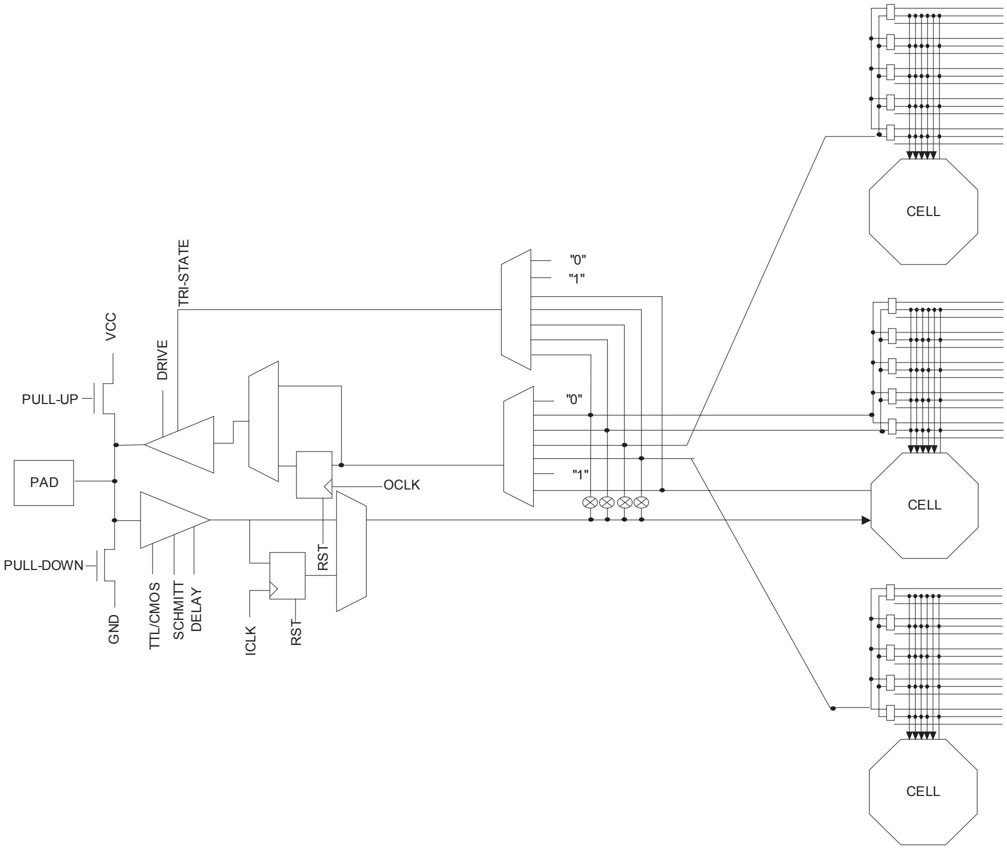
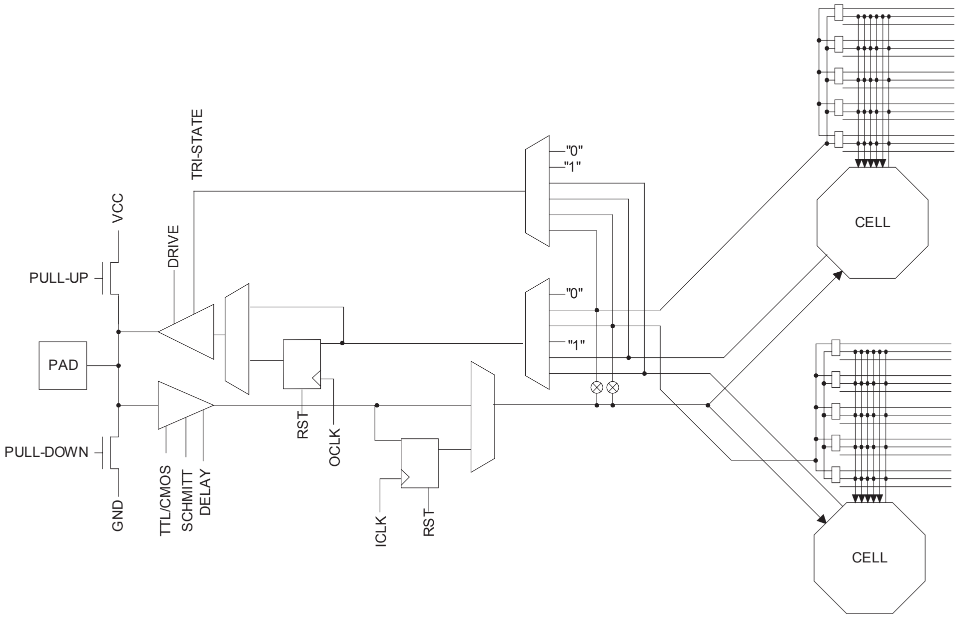


Figure 13. West Secondary I/O (Mirrored for East I/O)



Absolute Maximum Ratings – 3.3V Commercial/Industrial*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-0.5V to V_{CC} +7V
Supply Voltage (V_{CC})	-0.5V to +7.0V
Maximum Soldering Temp. (10 sec. @ 1/16 in.)	250°C
ESD (R_{ZAP} = 1.5K, C_{ZAP} = 100 pF)	2000V

*NOTICE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those listed under operating conditions is not implied. Exposure to Absolute Maximum Rating conditions for extended periods of time may affect device reliability.

DC and AC Operating Range – 3.3V Operation

		Commercial	Industrial
Operating Temperature (Case)		0°C - 70°C	-40°C - 85°C
V_{CC} Power Supply		3.3V ± 0.3V	3.3V ± 0.3V
Input Voltage Level (CMOS)	High (V_{IHC})	70% - 100% V_{CC}	70% - 100% V_{CC}
	Low (V_{ILC})	0 - 30% V_{CC}	0 - 30% V_{CC}

Power-On Power Supply Requirements

Atmel FPGAs require a minimum rated power supply current capacity to insure proper initialization, and the power supply ramp-up time does affect the current required. A fast ramp-up time requires more current than a slow ramp-up time.

Table 3. Power-On Power Supply Requirements(1)

Device	Description	Maximum Current(2)(3)
AT40K05AL AT40K10AL	Maximum Current Supply	50 mA
AT40K20AL AT40K40AL	Maximum Current Supply	100 mA

Notes:
1. This specification applies to Commercial and Industrial grade products only.
2. Devices are guaranteed to initialize properly at 50% of the minimum current listed above. A larger capacity power supply may result in a larger initialization current.
3. Ramp-up time is measured from 0 V DC to 3.6 V DC. Peak current required lasts less than 2 ms, and occurs near the internal power on reset threshold voltage.

AC Timing Characteristics – 3.3V Operation

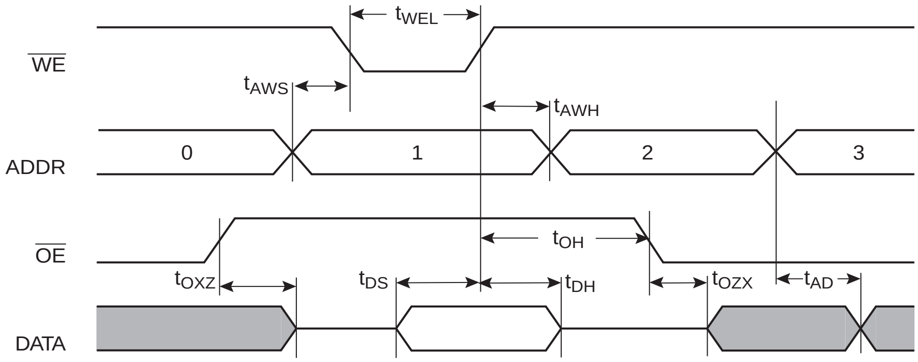
Delays are based on fixed loads and are described in the notes.
Maximum times based on worst case: V_{CC} = 3.0V, temperature = 70°C
Minimum times based on best case: V_{CC} = 3.6V, temperature = 0°C
Maximum delays are the average of t_{PDLH} and t_{PDHL}.

Clocks and Reset Input buffers are measured from a V_{IH} of 1.5V at the input pad to the internal V_{IH} of 50% of V_{CC}.
Maximum times for clock input buffers and internal drivers are measured for rising edge delays only.

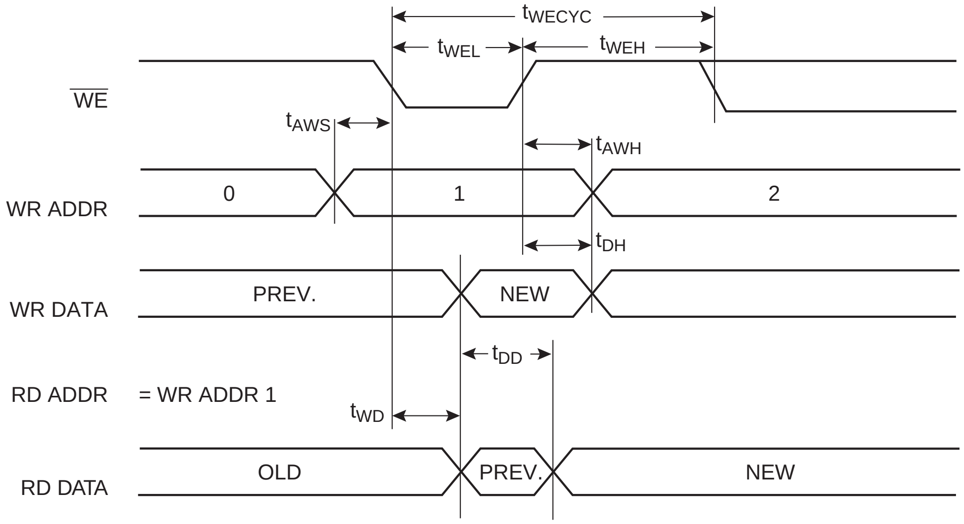
Cell Function	Parameter	Path	Device	-1	Units	Notes
Global Clocks and Set/Reset						
GCLK Input Buffer	t_{PD} (Maximum)	pad -> clock	AT40K05AL	1.1	ns	Rising edge clock
		pad -> clock	AT40K10AL	1.2	ns	
		pad -> clock	AT40K20AL	1.2	ns	
		pad -> clock	AT40K40AL	1.4	ns	
FCLK Input Buffer	t_{PD} (Maximum)	pad -> clock	AT40K05AL	0.7	ns	Rising edge clock
		pad -> clock	AT40K10AL	0.8	ns	
		pad -> clock	AT40K20AL	0.8	ns	
		pad -> clock	AT40K40AL	0.8	ns	
Clock Column Driver	t_{PD} (Maximum)	clock -> colclk	AT40K05AL	0.8	ns	Rising edge clock
		clock -> colclk	AT40K10AL	0.9	ns	
		clock -> colclk	AT40K20AL	1.0	ns	
		clock -> colclk	AT40K40AL	1.1	ns	
Clock Sector Driver	t_{PD} (Maximum)	colclk -> secclk	AT40K05AL	0.5	ns	Rising edge clock
		colclk -> secclk	AT40K10AL	0.5	ns	
		colclk -> secclk	AT40K20AL	0.5	ns	
		colclk -> secclk	AT40K40AL	0.5	ns	
GSRN Input Buffer	t_{PD} (Maximum)	pad -> GSRN	AT40K05AL	3.0	ns	From any pad to Global Set/Reset network
		pad -> GSRN	AT40K10AL	3.7	ns	
		pad -> GSRN	AT40K20AL	4.3	ns	
		pad -> GSRN	AT40K40AL	5.6	ns	
Global Clock to Output	t_{PD} (Maximum)	clock pad -> out	AT40K05AL	8.3	ns	Rising edge clock
		clock pad -> out	AT40K10AL	8.4	ns	Fully loaded clock tree
		clock pad -> out	AT40K20AL	8.6	ns	Rising edge DFF
		clock pad -> out	AT40K40AL	8.8	ns	20 mA output buffer
						50 pf pin load
Fast Clock to Output	t_{PD} (Maximum)	clock pad -> out	AT40K05AL	7.9	ns	Rising edge clock
		clock pad -> out	AT40K10AL	8.0	ns	Fully loaded clock tree
		clock pad -> out	AT40K20AL	8.1	ns	Rising edge DFF
		clock pad -> out	AT40K40AL	8.3	ns	20 mA output buffer
						50 pf pin load

FreeRAM Asynchronous Timing Characteristics

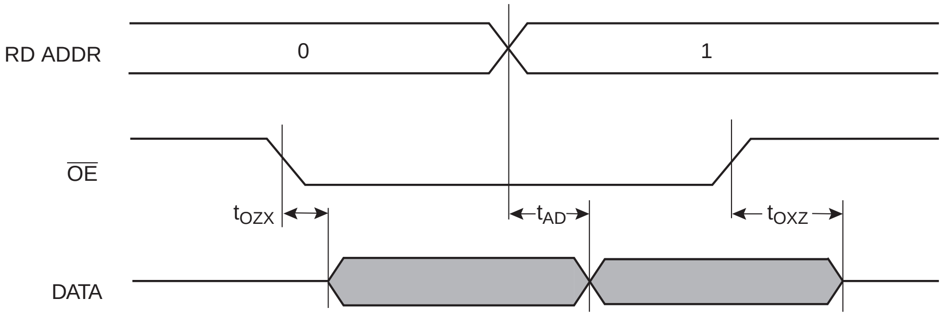
Single-port Write/Read



Dual-port Write with Read



Dual-port Read



AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Left Side (Top to Bottom)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
GND	GND	GND	GND	12	1	1	2	1
I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	I/O1, GCK1 (A16)	13	2	2	4	2
I/O2 (A17)	I/O2 (A17)	I/O2 (A17)	I/O2 (A17)	14	3	3	5	3
I/O3	I/O3	I/O3	I/O3			4	6	4
I/O4	I/O4	I/O4	I/O4			5	7	5
I/O5 (A18)	I/O5 (A18)	I/O5 (A18)	I/O5 (A18)	15	4	6	8	6
I/O6 (A19)	I/O6 (A19)	I/O6 (A19)	I/O6 (A19)	16	5	7	9	7
			GND					
			I/O7					
			I/O8					
			I/O9					
			I/O10					
		I/O7	I/O11					
		I/O8	I/O12					
		VCC	VCC					
		GND	GND					
			I/O13					
			I/O14					
I/O7	I/O7	I/O9	I/O15				10	8
I/O8	I/O8	I/O10	I/O16				11	9
	I/O9	I/O11	I/O17				12	10
	I/O10	I/O12	I/O18				13	11
			GND					
			I/O19					
			I/O20					
	I/O11	I/O13	I/O21					12
	I/O12	I/O14	I/O22					13
		I/O15	I/O23					
		I/O16	I/O24					
GND	GND	GND	GND			8	14	14

Note: 1. On-chip tri-state

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Left Side (Top to Bottom)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O9, FCK1	I/O13, FCK1	I/O17, FCK1	I/O25, FCK1			9	15	15
I/O10	I/O14	I/O18	I/O26			10	16	16
I/O11 (A20)	I/O15 (A20)	I/O19 (A20)	I/O27 (A20)	17	6	11	17	17
I/O12 (A21)	I/O16 (A21)	I/O20 (A21)	I/O28 (A21)	18	7	12	18	18
	VCC	VCC	VCC					19
	I/O17	I/O21	I/O29					20
	I/O18	I/O22	I/O30					21
			GND					
			I/O31					
			I/O32					
			I/O33					
			I/O34					
		I/O23	I/O35					
		I/O24	I/O36					
		GND	GND					22
			VCC					
			I/O37					
			I/O38					
		I/O25	I/O39					
		I/O26	I/O40					
	I/O19	I/O27	I/O41				19	23
	I/O20	I/O28	I/O42				20	24
			GND					
I/O13	I/O21	I/O29	I/O43			13	21	25
I/O14	I/O22	I/O30	I/O44		8	14	22	26
			I/O45					
			I/O46					
I/O15 (A22)	I/O23 (A22)	I/O31 (A22)	I/O47 (A22)	19	9	15	23	27
I/O16 (A23)	I/O24 (A23)	I/O32 (A23)	I/O48 (A23)	20	10	16	24	28
GND	GND	GND	GND	21	11	17	25	29
VCC	VCC	VCC	VCC	22	12	18	26	30

Note: 1. On-chip tri-state

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Left Side (Top to Bottom)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O17	I/O25	I/O33	I/O49	23	13	19	27	31
I/O18	I/O26	I/O34	I/O50	24	14	20	28	32
			I/O51					
			I/O52					
I/O19	I/O27	I/O35	I/O53		15	21	29	33
I/O20	I/O28	I/O36	I/O54			22	30	34
			GND					
	I/O29	I/O37	I/O55				31	35
	I/O30	I/O38	I/O56				32	36
		I/O39	I/O57					
		I/O40	I/O58					
			I/O59					
			I/O60					
			VCC					
		GND	GND					37
		I/O41	I/O61					
		I/O42	I/O62					
			I/O63					
			I/O64					
			I/O65					
			I/O66					
			GND					
	I/O31	I/O43	I/O67					38
	I/O32	I/O44	I/O68					39
	VCC	VCC	VCC					40
I/O21	I/O33	I/O45	I/O69	25	16	23	33	41
I/O22	I/O34	I/O46	I/O70	26	17	24	34	42
I/O23	I/O35	I/O47	I/O71			25	35	43
I/O24, FCK2	I/O36, FCK2	I/O48, FCK2	I/O72, FCK2			26	36	44
GND	GND	GND	GND			27	37	45
		I/O49	I/O73					
		I/O50	I/O74					
	I/O37	I/O51	I/O75					46

Note: 1. On-chip tri-state

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Bottom Side (Left to Right)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
VCC	VCC	VCC	VCC	33	25	37	55	61
M2	M2	M2	M2	34	26	38	56	62
I/O33, GCK3	I/O49, GCK3	I/O65, GCK3	I/O97, GCK3	35	27	39	57	63
I/O34 (HDC)	I/O50 (HDC)	I/O66 (HDC)	I/O98 (HDC)	36	28	40	58	64
I/O35	I/O51	I/O67	I/O99			41	59	65
I/O36	I/O52	I/O68	I/O100			42	60	66
I/O37	I/O53	I/O69	I/O101		29	43	61	67
I/O38 (LDC)	I/O54 (LDC)	I/O70 (LDC)	I/O102 (LDC)	37	30	44	62	68
			GND					
			I/O103					
			I/O104					
			I/O105					
			I/O106					
		I/O71	I/O107					
		I/O72	I/O108					
		VCC	VCC					
		GND	GND					
I/O39	I/O55	I/O73	I/O109				63	69
I/O40	I/O56	I/O74	I/O110				64	70
	I/O57	I/O75	I/O111				65	71
	I/O58	I/O76	I/O112				66	72
			I/O113					
			I/O114					
			GND					
		I/O77	I/O115					
		I/O78	I/O116					
	I/O59	I/O79	I/O117					73
	I/O60	I/O80	I/O118					74
			I/O119					
			I/O120					
GND	GND	GND	GND			45	67	75
I/O41	I/O61	I/O81	I/O121			46	68	76

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Right Side (Bottom to Top)				
128 I/O	**192 I/O**	**256 I/O**	**384 I/O**	**84 PLCC**	**100 TQFP**	**144 LQFP**	**208 PQFP**	**240 PQFP**
VCC	VCC	VCC	VCC	54	51	73	106	121
$\overline{\text{RESET}}$	$\overline{\text{RESET}}$	$\overline{\text{RESET}}$	$\overline{\text{RESET}}$	55	52	74	108	122
I/O65 (D7)	I/O97 (D7)	I/O129 (D7)	I/O193 (D7)	56	53	75	109	123
I/O66, GCK5	I/O98, GCK5	I/O130, GCK5	I/O194, GCK5	57	54	76	110	124
I/O67	I/O99	I/O131	I/O195			77	111	125
I/O68	I/O100	I/O132	I/O196			78	112	126
		I/O133	I/O197					
		I/O134	I/O198					
			GND					
	I/O101	I/O135	I/O199					127
	I/O102	I/O136	I/O200					128
			I/O201					
			I/O202					
			I/O203					
			I/O204					
		VCC	VCC					
		GND	GND					
I/O69 (D6)	I/O103 (D6)	I/O137 (D6)	I/O205 (D6)	58	55	79	113	129
I/O70	I/O104	I/O138	I/O206		56	80	114	130
I/O71	I/O105	I/O139	I/O207				115	131
I/O72	I/O106	I/O140	I/O208				116	132
			I/O209					
			I/O210					
			GND					
			I/O211					
			I/O212					
	I/O107	I/O141	I/O213				117	133
	I/O108	I/O142	I/O214				118	134
		I/O143	I/O215					
		I/O144	I/O216					
GND	GND	GND	GND			81	119	135
	I/O109	I/O145	I/O217					136
	I/O110	I/O146	I/O218					137

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
GND	GND	GND	GND	76	77	110	160	182
I/O97 (A0)	I/O145 (A0)	I/O193 (A0)	I/O289 (A0)	77	78	111	161	183
I/O98, GCK7 (A1)	I/O146, GCK7 (A1)	I/O194, GCK7 (A1)	I/O290, GCK7 (A1)	78	79	112	162	184
I/O99	I/O147	I/O195	I/O291			113	163	185
I/O100	I/O148	I/O196	I/O292			114	164	186
			I/O293					
			I/O294					
			GND					
			I/O295					
			I/O296					
I/O101 ($\overline{CS1}$,A2)	I/O149 ($\overline{CS1}$,A2)	I/O197 ($\overline{CS1}$,A2)	I/O297 ($\overline{CS1}$,A2)	79	80	115	165	187
I/O102 (A3)	I/O150 (A3)	I/O198 (A3)	I/O298 (A3)	80	81	116	166	188
		I/O199	I/O299					
		I/O200	I/O300					
		VCC	VCC					
		GND	GND					
	I/O151(1)	I/O201(1)	I/O301(1)	75(1) NC	76(1) NC	109(1) NC	159(1) NC	189(1) NC
	I/O152	I/O202	I/O302					190
I/O103	I/O153	I/O203	I/O303			117	167	191
I/O104(1)	I/O154	I/O204	I/O304				168	192
			I/O305					
			I/O306					
			GND					
			I/O307					
			I/O308					
	I/O155	I/O205	I/O309				169	193
	I/O156	I/O206	I/O310				170	194
		I/O207	I/O311					195
		I/O208	I/O312					
GND	GND	GND	GND			118	171	196

Note: 1. Shared with TSTCLK. No Connect.

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O105	I/O157	I/O209	I/O313			119	172	197
I/O106	I/O158	I/O210	I/O314			120	173	198
	I/O159	I/O211	I/O315					199
	I/O160	I/O212	I/O316					200
	VCC	VCC	VCC					201
		I/O213	I/O317					
		I/O214	I/O318					
			GND					
			I/O319					
			I/O320					
			I/O321					
			I/O322					
		I/O215	I/O323					
		I/O216	I/O324					
		GND	GND					
			VCC					
I/O107 (A4)	I/O161 (A4)	I/O217 (A4)	I/O325 (A4)	81	82	121	174	202
I/O108 (A5)	I/O162 (A5)	I/O218 (A5)	I/O326 (A5)	82	83	122	175	203
	I/O163	I/O219	I/O327				176	205
	I/O164	I/O220	I/O328				177	206
I/O109	I/O165	I/O221	I/O329		84	123	178	207
I/O110	I/O166	I/O222	I/O330		85	124	179	208
			GND					
			I/O331					
			I/O332					
			I/O333					
			I/O334					
I/O111 (A6)	I/O167 (A6)	I/O223 (A6)	I/O335 (A6)	83	86	125	180	209
I/O112 (A7)	I/O168 (A7)	I/O224 (A7)	I/O336 (A7)	84	87	126	181	210
GND	GND	GND	GND	1	88	127	182	211
VCC	VCC	VCC	VCC	2	89	128	183	212

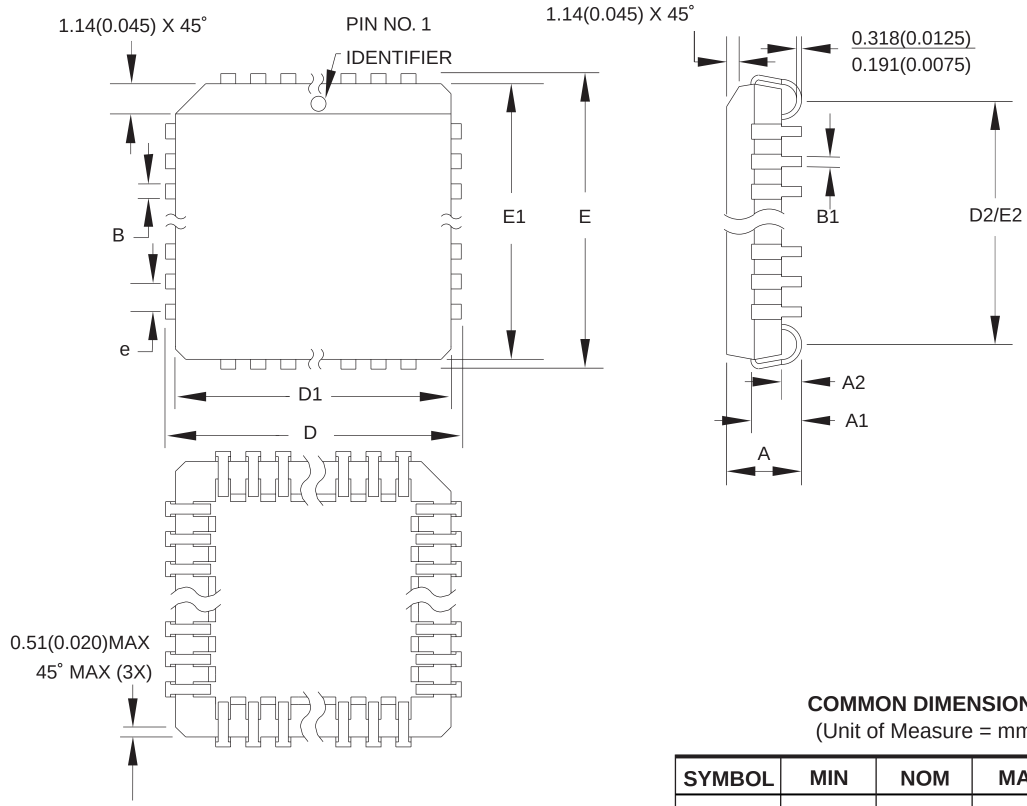
Note: 1. Shared with TSTCLK. No Connect.

AT40K05AL	AT40K10AL	AT40K20AL	AT40K40AL	Top Side (Right to Left)				
128 I/O	192 I/O	256 I/O	384 I/O	84 PLCC	100 TQFP	144 LQFP	208 PQFP	240 PQFP
I/O113 (A8)	I/O169 (A8)	I/O225 (A8)	I/O337 (A8)	3	90	129	184	213
I/O114 (A9)	I/O170 (A9)	I/O226 (A9)	I/O338 (A9)	4	91	130	185	214
			I/O339					
			I/O340					
			I/O341					
			I/O342					
			GND					
I/O115	I/O171	I/O227	I/O343		92	131	186	215
I/O116	I/O172	I/O228	I/O344		93	132	187	216
	I/O173	I/O229	I/O345				188	217
	I/O174	I/O230	I/O346				189	218
I/O117 (A10)	I/O175 (A10)	I/O231 (A10)	I/O347 (A10)	5	94	133	190	220
I/O118 (A11)	I/O176 (A11)	I/O232 (A11)	I/O348 (A11)	6	95	134	191	221
			VCC					
		GND	GND					
		I/O233	I/O349					
		I/O234	I/O350					
			I/O351					
			I/O352					
			I/O353					
			I/O354					
			GND					
		I/O235	I/O355					
		I/O236	I/O356					
	VCC	VCC	VCC					222
	I/O177	I/O237	I/O357					223
	I/O178	I/O238	I/O358					224
I/O119	I/O179	I/O239	I/O359			135	192	225
I/O120	I/O180	I/O240	I/O360			136	193	226
GND	GND	GND	GND			137	194	227
		I/O241	I/O361					

Note: 1. Shared with TSTCLK. No Connect.

Packaging Information

84J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

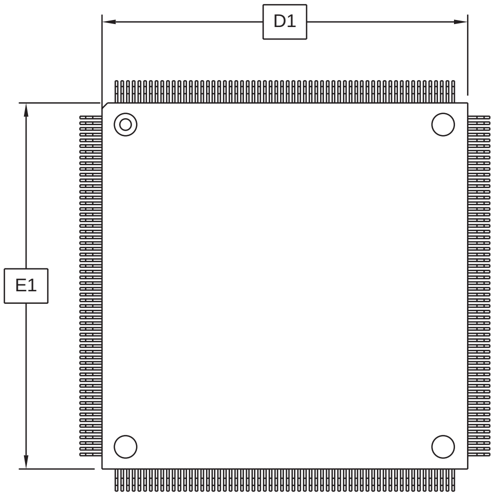
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	30.099	–	30.353	
D1	29.210	–	29.413	Note 2
E	30.099	–	30.353	
E1	29.210	–	29.413	Note 2
D2/E2	27.686	–	28.702	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AF.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

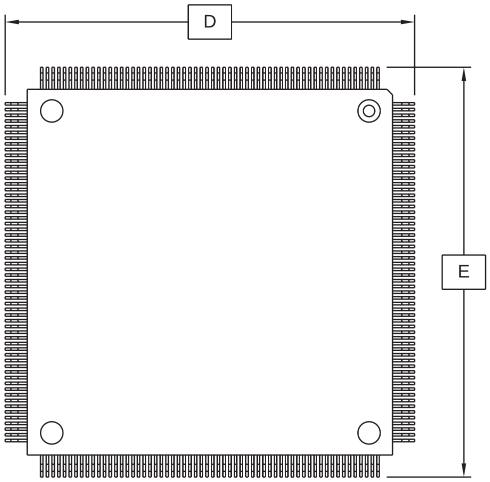
10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**84J**, 84-lead, Plastic J-leaded Chip Carrier (PLCC)	84J	B

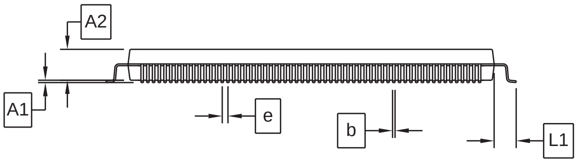
240Q1 – PQFP



Top View



Bottom View



Side View

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A1	0.25	–	0.50	
A2	3.20	3.40	3.60	
D	34.60 BSC			3
D1	32.00 BSC			2, 4
E	34.60 BSC			3
E1	32.00 BSC			2, 4
e	0.50 BSC			
b	0.17	–	0.27	5
L1	1.30 REF			

Notes:
1. This drawing is for general information only. Refer to JEDEC Drawing MS-029, Variation GA, for additional information.
2. All dimensioning and tolerancing conforms to ASME Y14.5M-1994.
3. To be determined at seating plane.
4. Dimensions D1 and E1 do not include mold protrusions. Allowable protrusion is 0.25 mm per side. D1 and E1 are maximum plastic body size dimensions including mold mismatch. Dimensions D1 and E1 shall be determined at datum plane.
5. Dimension b does not include Dambar protrusion. Allowable Dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08 mm. Dambar cannot be located on the lower radius or the foot. The minimum space between protrusion and an adjacent lead shall not be less than 0.07 mm.

3/29/02

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**240Q1,** 240-lead, 32 x 32 mm Body, 2.6 Form Opt., Plastic Quad Flat Pack (PQFP)	240Q1	A

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